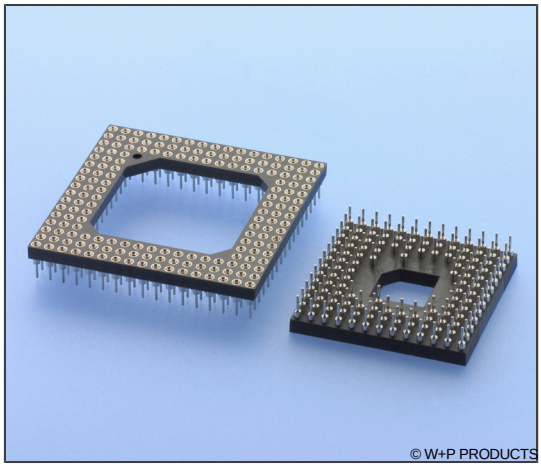
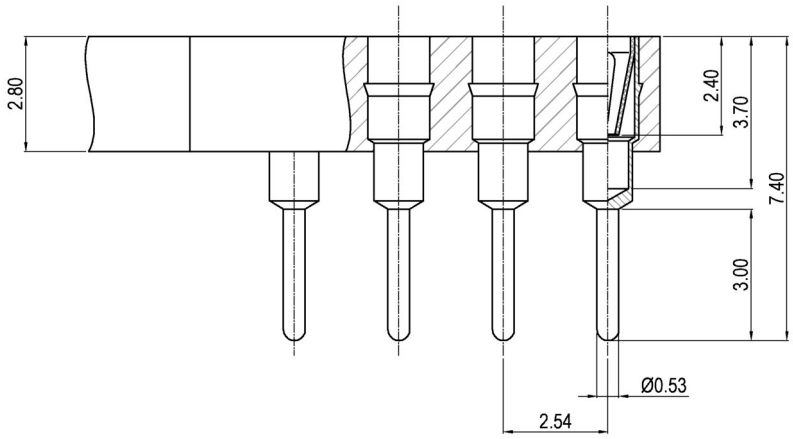
195
PGA-Fassungen
PGA-Sockets

Technische Daten / *Technical Data*

Gehäuse/Abdeckung/Hebel	Thermoplast, nach UL94 V-0
Case/Cover/Actuator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Hülse: Messing gedreht Feder: 4-Lamellen-Clip, Beryllium-Kupfer
Contact Material	*Sleeve: screw machined brass* *Clip: 4-Finger-Clip, Beryllium-Copper*
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni
Contact Surface	*Acc. to options (see below), over Ni*
RoHS-Ausnahmen 6a-I / 6c	keine
RoHS Exemptions 6a-I / 6c	*none*
Durchgangswiderstand	< 10 mΩ
Contact Resistance	*< 10 mΩ*
Isolationswiderstand	> 1000 MΩ
Insulation Resistance	*> 1000 MΩ*
Spannungsfestigkeit	1 kV RMS
Withstanding Voltage	*1 kV RMS*
Nennspannung	100 V RMS / 150 V DC
Voltage Rating	*100 V RMS / 150 V DC*
Nennstrom	1 A
Current Rating	*1 A*
Temperaturbereich	-55 °C ... +125 °C
Temperature Range	*-55 °C ... +125 °C*
Verarbeitung	Wellen- oder Reflow-Lötverfahren
Processing	*Wave or reflow soldering*



Einsetzbar für Rundstifte Ø 0,4 - 0,56mm
oder für Vierkantstifte 0,25 x 0,45mm.
Accept round pins Ø 0.4 - 0.56mm
or rectangular pins 0.25mm x 0.45mm.



Series	***Contacts****	***Grid****	***Version***	***Sleeve Plating****	***Clip Plating****
195	**084**	**11**	**0**	**50**	**00**

Grid* :
11 11x11
13 13x13
15 15x15
17 17x17

Sleeve Plating* :
50 Verzinnt (Standard)
Tin plated (Standard)
10 Vergoldet 0,25µm
0.25µm gold plated

Clip Plating* :
00 Vergoldet
Gold plated
10 Vergoldet 0,25µm (Option)
0.25µm gold plated (Option)
30 Vergoldet 0,75µm
0.75µm gold plated

Weitere Layouts, Clips, Raster und Datenblätter auf Anfrage.
More layouts, clips, pitches and data sheets on request.

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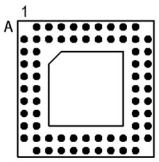
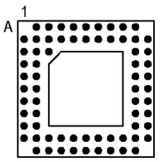
PGA-Fassungen
PGA-Sockets

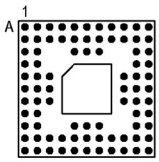
11x11



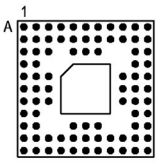
68 Contacts



69 Contacts

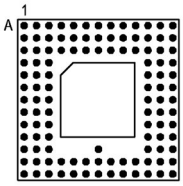


84 Contacts

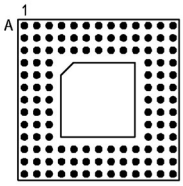


85 Contacts

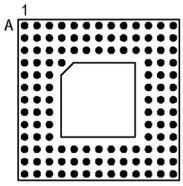
13x13



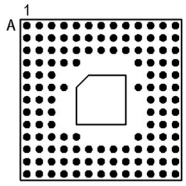
114 Contacts



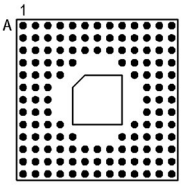
120 Contacts



121 Contacts

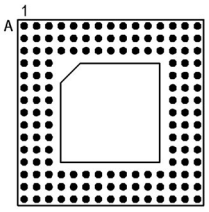


128 Contacts

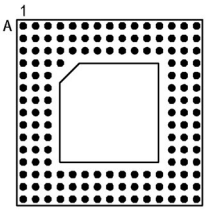


132 Contacts

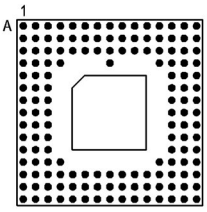
15x15



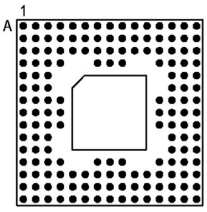
144 Contacts



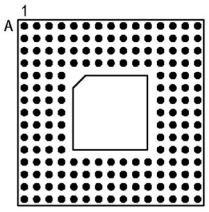
145 Contacts



149 Contacts

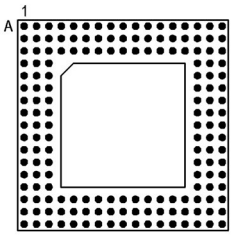


160 Contacts

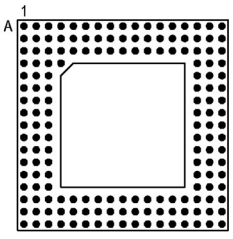


176 Contacts

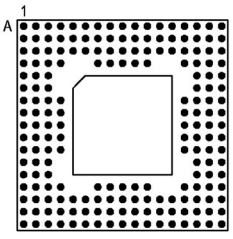
17x17



168 Contacts



169 Contacts



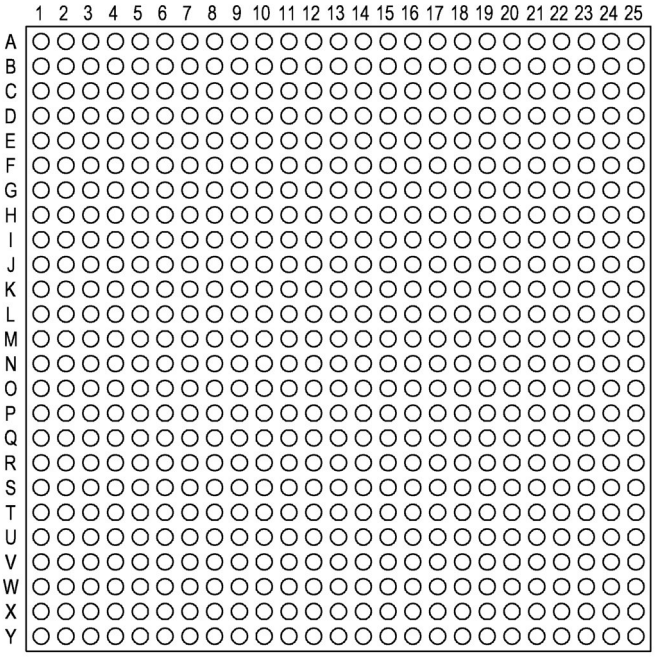
192 Contacts

Ihr Wunschraster

Bitte markieren Sie die Bestückungspositionen.

Your Own Grid

Please mark the contact positions.



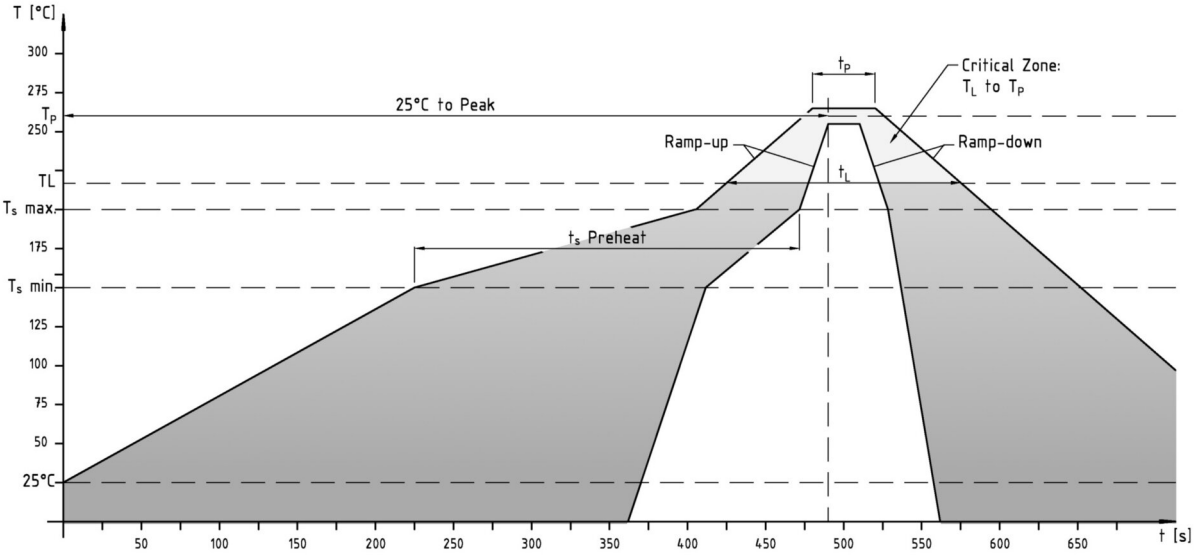
* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

Reflow-Lötempfehlung für kurze Lötzeiten

Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150 °C
Temperatur Maximum $T_S$max	200 °C
Dauer $T_S$min – $T_S$max	60 – 180s
Temperatur Lötbereich T_L	217 °C
Verweildauer oberhalb T_L	60 – 180s
Ramp-Up Rate $T_S$max – T_P	max. 3 °C / s
Höchsttemperatur T_P	260±5 °C
Dauer Höchsttemperatur	20 – 40s
Ramp-Down Rate $T_P$max – $T_S$min	6 °C / s
Dauer 25 °C – Höchsttemperatur T_P	max. 8m

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_S$min	*150 °C*
Maximum Temperatur $T_S$max	*200 °C*
Duration $T_S$min – $T_S$max	*60 – 180s*
Soldering Range Temperature T_L	*217 °C*
Duration above T_L	*60 – 180s*
Ramp-Up Rate $T_S$max – T_P	*max. 3 °C / s*
Peak Temperature T_P	*260±5 °C*
Duration Peak Temperature	*20 – 40s*
Ramp-Down Rate $T_P$max – $T_S$min	*6 °C / s*
Duration 25°C - Peak Temp. T_P	*max. 8min*